

**• General Description**

The TF060N10NG uses advanced trench technology and design to provide excellent RDS(ON) with lowgate charge. It can be used in a wide variety of applications.

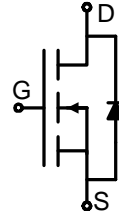
**• Features**

- Advance device constructure
- Low R<sub>DS(ON)</sub> to minimize conduction loss
- Low Gate Charge for fast switching
- Low Thermal resistance

**• Application**

- Synchronous Rectification for AC-DC/DC-DC converter
- Power Tools

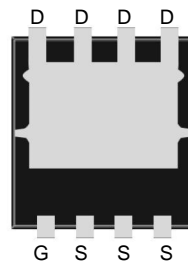
**• Product Summary**



$V_{DS} = 100V$   $I_D = 82A$

$R_{DS(ON)(10V\ typ)} = 5.9m\Omega$

$R_{DS(ON)(4.5V\ typ)} = 7.6m\Omega$



**PDFN5x6-8L**

**• Package Marking and Ordering Information:**

Part NO.	TF060N10NG
Marking1	060N10NG
Marking2	TF:tuofeng; AA:device code; Y:year code; X:Week
Basic ordering unit	5000 / PCS

**• Absolute Maximum Ratings (T<sub>C</sub> = 25°C)**

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V <sub>DS</sub>	100	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Continuous Drain Current	I <sub>D@TC=25°C</sub>	82	A
	I <sub>D@TC=75°C</sub>	57	A
	I <sub>D@TC=100°C</sub>	49	A
Pulsed Drain Current ①	I <sub>DM</sub>	328	A
Total Power Dissipation	P <sub>D@TC=25°C</sub>	108	W
Total Power Dissipation	P <sub>D@TA=25°C</sub>	2.0	W
Operating Junction Temperature	T <sub>J</sub>	-55 to 150	°C
Storage Temperature	T <sub>STG</sub>	-55 to 150	°C
Single Pulse Avalanche Energy	E <sub>AS</sub>	245	mJ

Note: ① Pulse Test : Pulse width ≤ 300μs, Duty cycle ≤ 2% ;



TUO FENG

Shenzhen Tuofeng Semiconductor Technology Co., Ltd

**N-CHANNEL ENHANCEMENT MODE POWER MOSFET**

**SGT MOS、低内阻、低结电容开关损耗小**

**TF060N10NG**

●Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	$R_{thJC}$	-	-	4.8	° C/W
Thermal resistance, junction - ambient	$R_{thJA}$	-	-	50	° C/W
Soldering temperature, wavesoldering for 8 s	$T_{sold}$	-	-	265	° C

●Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	100	-	-	V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 250\mu A$	1.2	1.7	2.3	V
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS} = 100V, V_{GS} = 0V$	-	-	1.0	$\mu A$
Gate- Source Leakage Current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	$\pm 100$	nA
Static Drain-source On Resistance	$R_{DS(ON)}$	$V_{GS} = 10V, I_D = 20A$	-	5.9	8.0	m $\Omega$
		$V_{GS} = 4.5V, I_D = 15A$	-	7.6	9.5	m $\Omega$
Forward Transconductance	$g_{FS}$	$V_{DS} = 25V, I_D = 20A$	-	18	-	S
Source-drain voltage	$V_{SD}$	$I_S = 20A$	-	-	1.20	V

●Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Input capacitance	$C_{iss}$	$f = 1MHz$ $V_{DS} = 50V$	-	1585	-	pF
Output capacitance	$C_{oss}$		-	693	-	
Reverse transfer capacitance	$C_{rss}$		-	13	-	

●Gate Charge characteristics( $T_a = 25^\circ C$ )

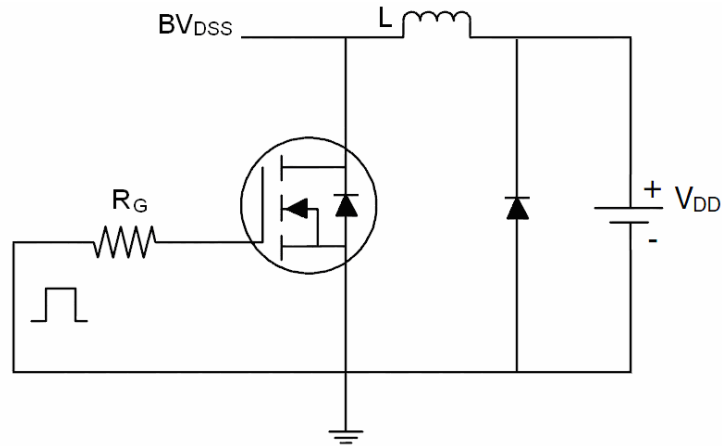
Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Total gate charge	$Q_g$	$V_{DD} = 50V$ $I_D = 20A$ $V_{GS} = 10V$	-	27.0	-	nC
Gate - Source charge	$Q_{gs}$		-	13.2	-	
Gate - Drain charge	$Q_{gd}$		-	5.3	-	

●Switching Characteristics

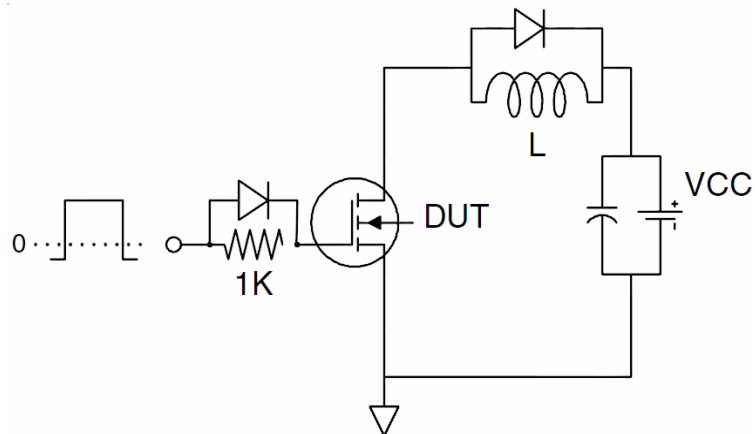
Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 50V$ $I_D = 20A$ $R_G = 3.0$ $V_{GS} = 10V$	-	4.6	-	nS
Rise time	$t_r$		-	10	-	
Turn-off delay time	$t_{d(off)}$		-	23	-	
Fall time	$t_f$		-	21	-	

**Test Circuit**

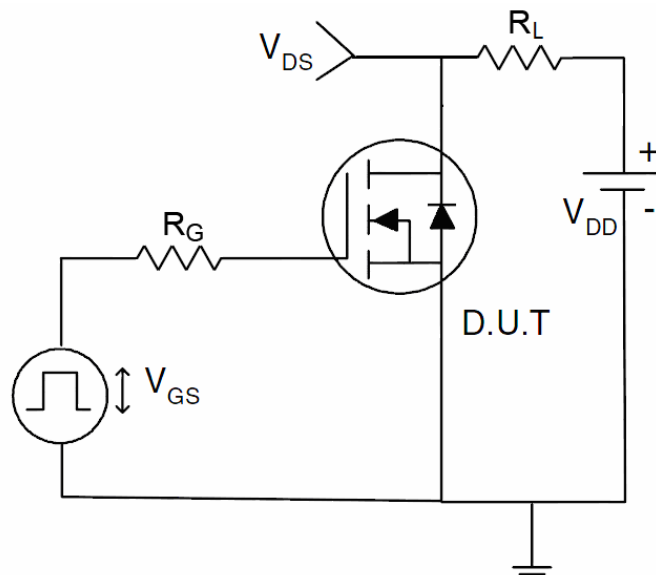
**1) E<sub>AS</sub> test Circuit**



**2) Gate charge test Circuit**



**3) Switch Time Test Circuit**



Typical Performance Characteristics

Fig 1: Output Characteristics

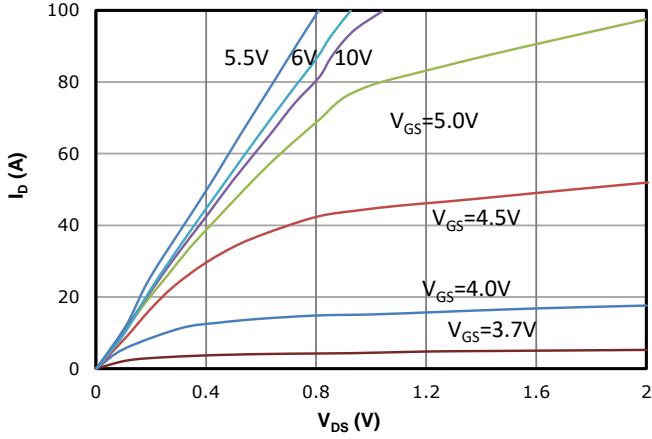


Fig 2: Transfer Characteristics

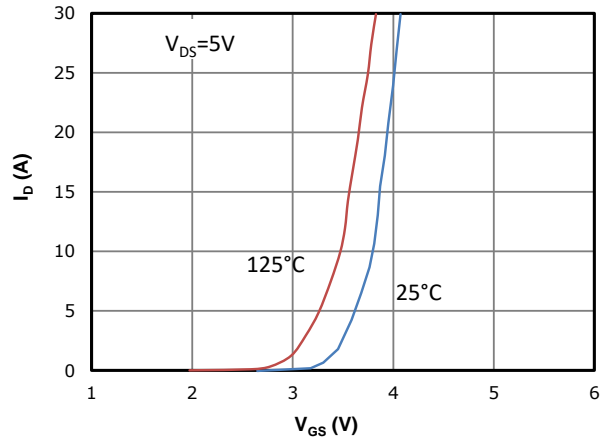


Fig 3: Rds(on) vs Drain Current and Gate Voltage

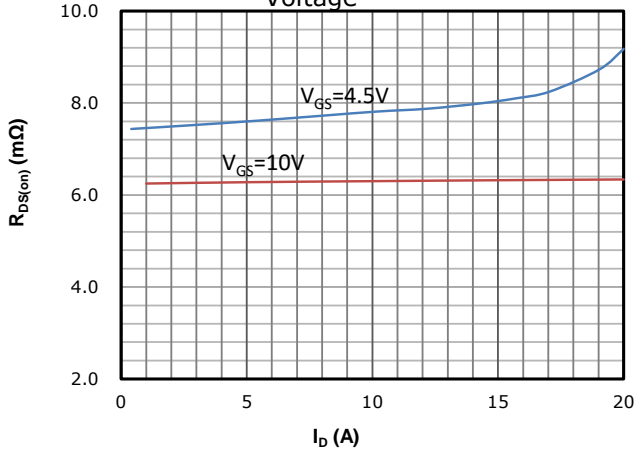


Fig 4: Rds(on) vs Gate Voltage

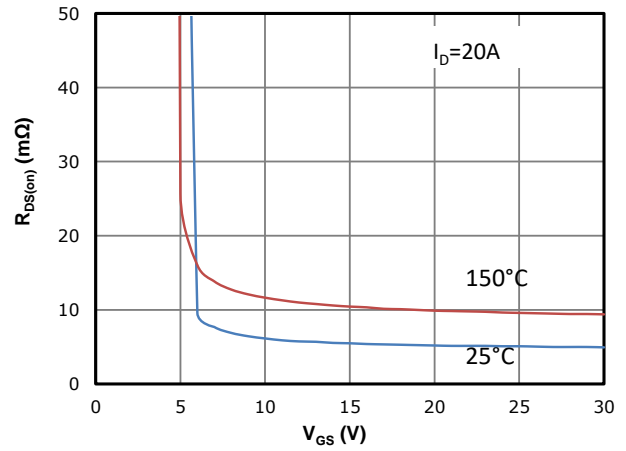


Fig 5: Rds(on) vs. Temperature

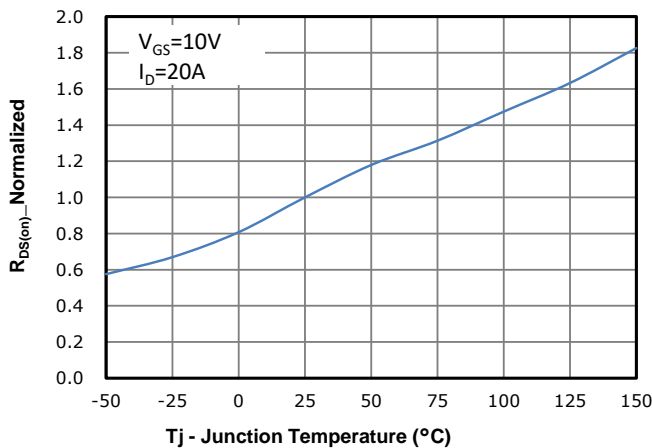


Fig 6: Vgs(th) vs. Temperature

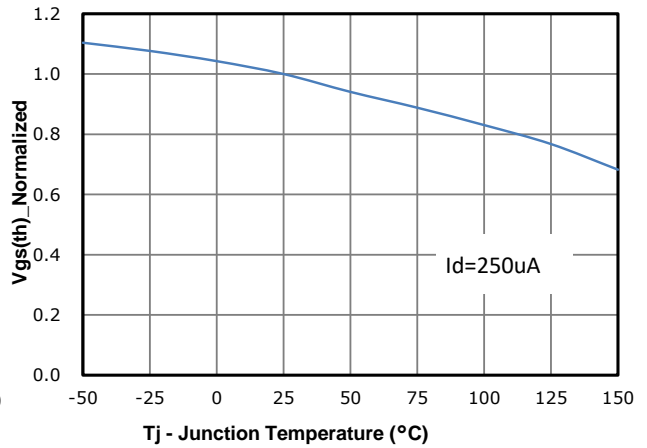


Fig 7: BVdss vs. Temperature

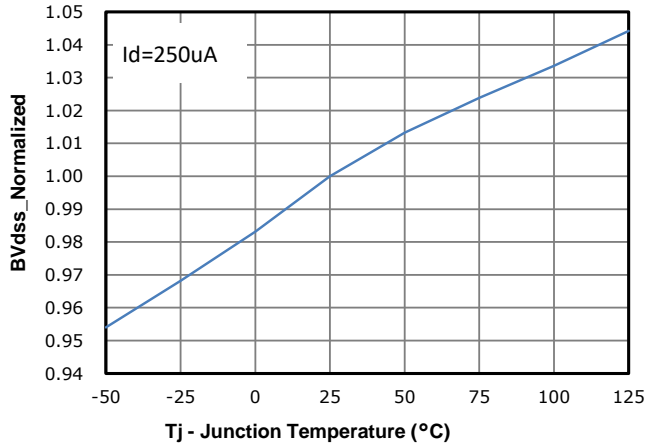


Fig 8: Capacitance Characteristics

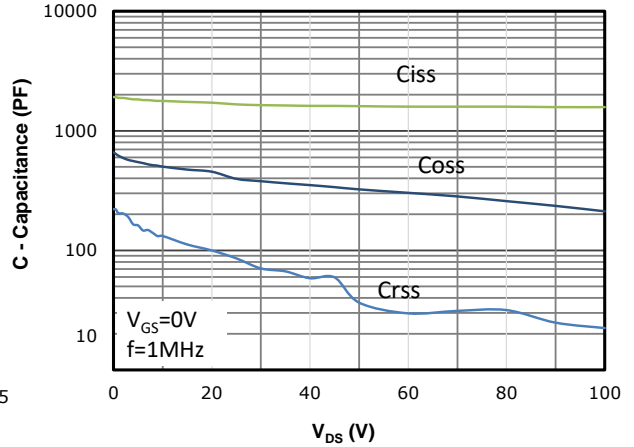


Fig 9: Gate Charge Characteristics

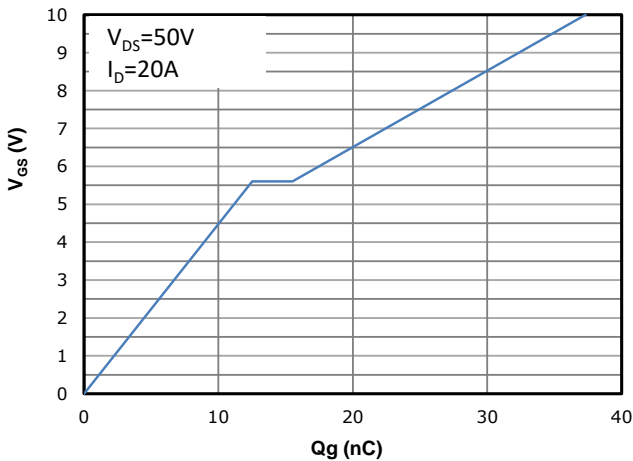


Fig 10: Body-diode Forward Characteristics

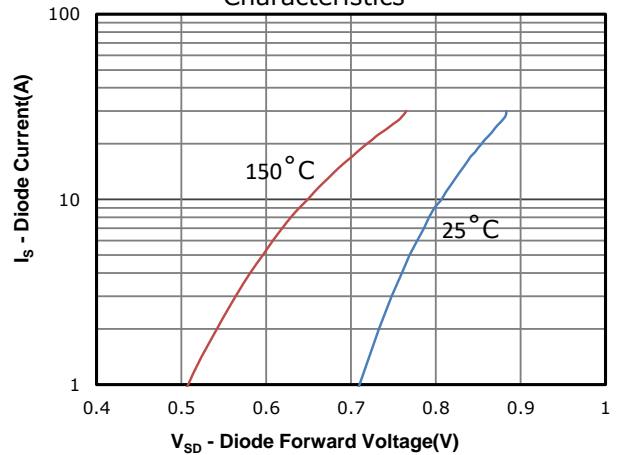


Fig 11: Power Dissipation

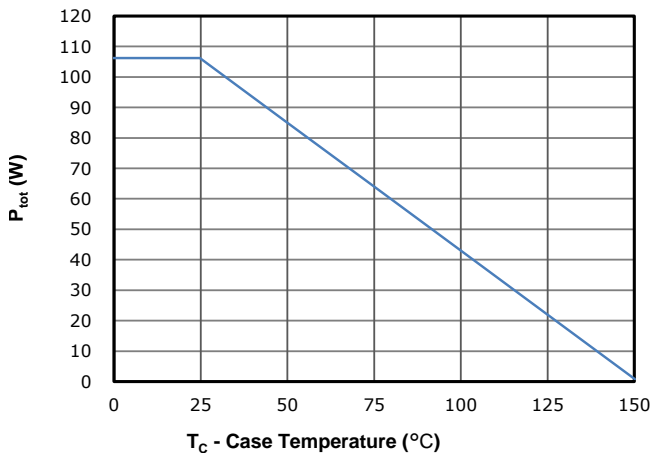


Fig 12: Drain Current Derating

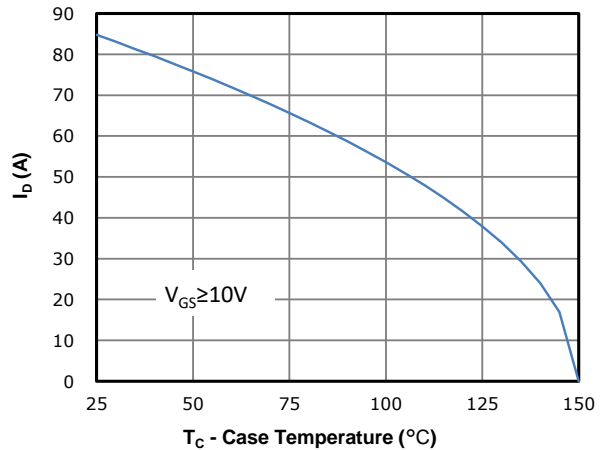


Fig 13: Safe Operating Area

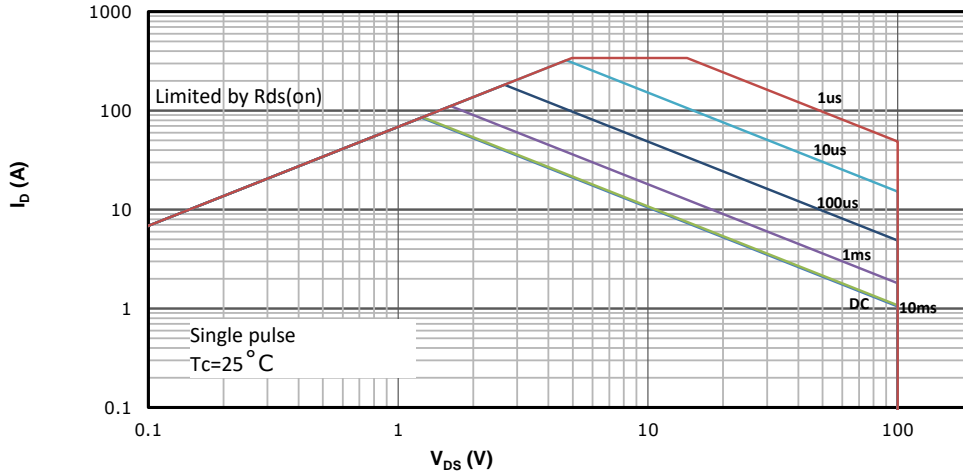
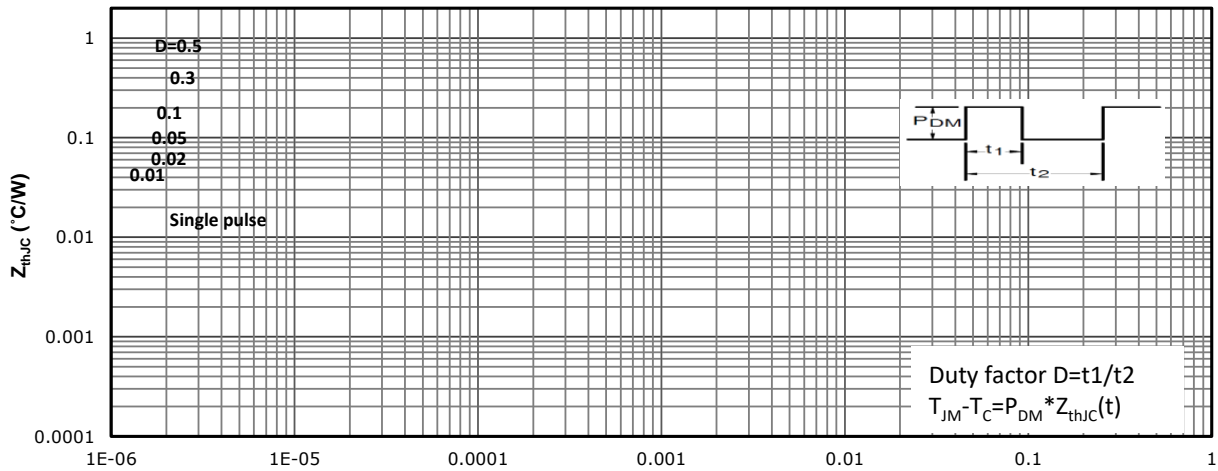
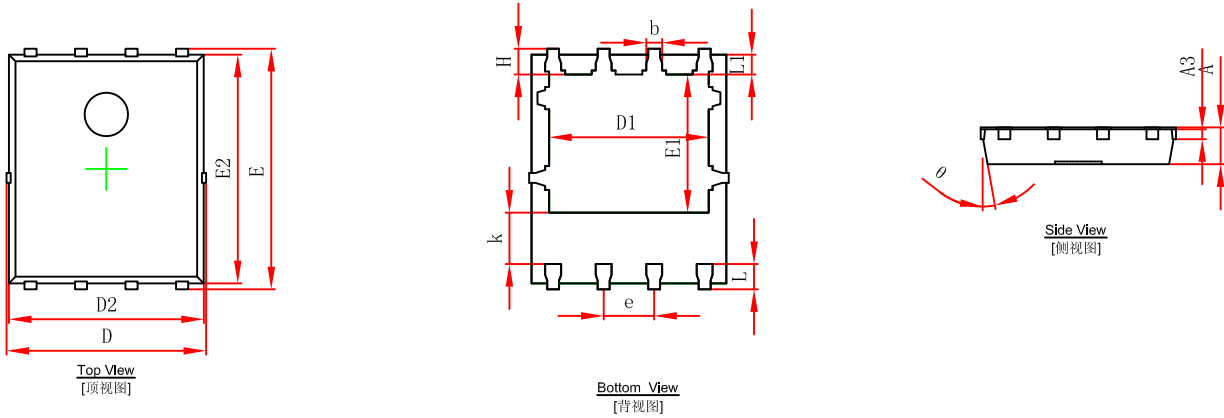


Fig 14: Max. Transient Thermal Impedance

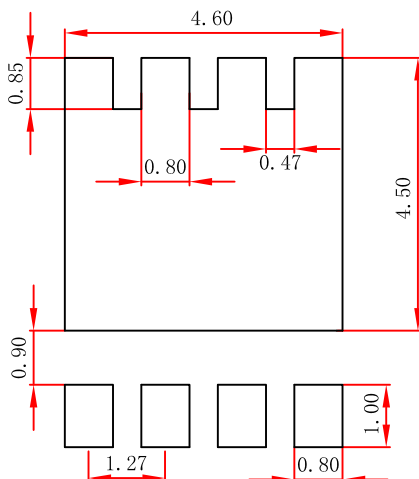


PDFN5x6-8L Package Outline Dimenslons



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.254REF.		0.010REF.	
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	3.910	4.110	0.154	0.162
E1	3.375	3.575	0.133	0.141
D2	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
e	1.270TYP.		0.050TYP.	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
θ	10°	12°	10°	12°

PDFN5x6-8L Suggested Pad Layout



Note:  
 1. Controlling dimension: in millimeters.  
 2. General tolerance: ±0.05mm.  
 3. The pad layout is for reference purposes only.